

ABSTRACT OF THE DISCLOSURE

In one embodiment, a method of forming a metallic electrode comprises depositing a metal layer over a surface (e.g., substrate) and thermally processing the metal layer to form a conductive metallized ceramic. The metal layer may be deposited by sputtering and thermally processed by rapid thermal processing, for example. Among other advantages, embodiments of the present invention allow for the formation of conductive metallized ceramics, such as titanium-nitride, without the use of relatively expensive deposition tools.

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